

Application No. 09/681,304

RD-28435

i hereby certify that this correspondence (5 sheets total) is being
facsimile transmitted to the TC2800 After Final Facsimile Number
703-872-9319 of the United States Patent and Trademark Office
on 22 October 2002.

Typed or printed name: Ann M. Agosti

Signature: *Ann M. Agosti*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: R.J. Saia et al.
Application No. 09/681,304
Filed: 15 March 2001

: Group Art Unit: 2814
: Examiner: D. Nguyen
: Response to Paper No. 8

TECHNOLOGY CENTER 2800

For **Microelectromechanical System
Device Package and Packaging Method**

AMENDMENT UNDER 37 CFR 1.111

Assistant Commissioner for Patents
Washington, DC 20231

In response to the Office Action dated 26 August 2002, please amend the above-identified
application as follows.

IN THE TITLE:

Replacement Title: Microelectromechanical System Device Packaging Method

IN THE CLAIMS:

Please rewrite claims 4 and 6 as follows:

Claim 4 (amended two times). The method of claim 1, wherein attaching the MEMS device
comprises using the adhesive.

Claim 6 (amended two times). The method of claim 1, wherein the adhesive comprises a mixture
of photodielectric and epoxy materials.

9/18/02
G. Stanley
FAX COPY RECEIVED
OCT 22 2002
10-29-02